

RESPONSE TO RESTRICTION REQUIREMENT AND PRELIMINARY AMENDMENT

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Serial Number: 10/607,782

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Title: LIQUID SOLDER THERMAL INTERFACE MATERIAL CONTAINED WITHIN A COLD-FORMED BARRIER AND METHODS OF MAKING SAME

Assignee: Intel Corporation

REMARKS

Claim 27 was amended; claims 19-26 were withdrawn; as a result, claims 1-29 are now pending in this application.

No new matter was added by these amendments.

The Examiner is invited to telephone Applicant's attorney, John Greaves at (810) 278-9171, or Applicant's below-named representative to facilitate the prosecution of this application. If necessary, please charge any additional fees or credit overpayment to Deposit Account No. 19-0743.

Respectfully submitted,

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By his Representatives,

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Date

October 20, 2004

By

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Reg. No. 25,179

CERTIFICATE UNDER 37 CFR 1.8: The undersigned hereby certifies that this correspondence is being deposited with the United States Postal Service with sufficient postage as first class mail, in an envelope addressed to: MS Amendment, Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450 on this ___20th___ day of October, 2004.

Chris Hammond

Name

Signature

Chris Hammond